L Number	Hits	Search Text	DB	Time stamp
1	2998	257/697 438/612	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:10
2	56	(257/697 438/612) and jig	USPAT; US-PGPUB; EPO; JPO;	2002/07/14 18:48
3	12	("4021838" "4074342" "4338621" "4561006" "4823234" "4866841" "4893174" "4953060" "5006922" "5016087" "5025347" "5266912").PN.	DERWENT USPAT	2002/07/14 18:53
4	4	5485039.URPN.	USPAT	2002/07/14 18:54
5	2	3654694.URPN.	USPAT	2002/07/14 18:56
6	7	6001724.URPN.	USPAT	2002/07/14 18:57
7	0	6165888.URPN.	USPAT	2002/07/14 18:59
8	21	("4603802" "4661192" "4907734" "5014111" "5201454" "5249450" "5293073" "5302550" "5421503" "5550407" "5558270" "5633204" "5740956" "5871141" "5874780" "5884830" "5938105" "6001724" "6041995" "6080651" "6098868").PN.	USPAT	2002/07/14 18:59
9	13	5874780.URPN.	USPAT	2002/07/14 19:04
10	1	6204089.URPN.	USPAT	2002/07/14 19:07
11	9	("5376584" "5468655" "5478007" "5795818" "5854514" "5874780" "5894173" "5916407" "6005292").PN.	USPAT	2002/07/14 19:07
12	1	"5874780".PN.	USPAT	2002/07/14 19:08
13	7	("5037780" "5070604" "5348214" "5410807" "5478007" "5518964" "5615824").PN.	USPAT	2002/07/14 19:09
14	1121	257/697	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:11
15	790	257/697 and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:11
16	422	(257/697 and (method process)) and solder and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:12
17	297	((257/697 and (method process)) and solder and pad) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:13
18	283	(((257/697 and (method process)) and solder and pad) and pin) not ((257/697 438/612) and jig)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14
19	19	"4498725" "4773873" "4950980" "5384692" "5637008" "5669774" "5691041" "5707247" "5714803" "5749999" "5766021" "5783461" "5805419" "5808474" "5812378"	USPAT	2002/07/14 19:15
20	1	"6069023").PN. 6229207.URPN.	USPAT	2002/07/14

21	1	6229207.URPN.	USPAT	2002/07/14
	0.0	("4170472" "4290079" "4824009"	USPAT	19:21 2002/07/14
22	20	"5102829" "5237130" "5288944"	OSFAI	19:21
		"5303862" "5468995" "5541450"		13.21
		"5625166" "5625944" "5640047"		
		"5641990" "5831336" "5834839"		
		"5847929" "5868304" "5907187"		
		"5938862" "5959348").PN.		
23	15	5288944.URPN.	USPAT	2002/07/14
25				19:23
24	3	("4338621" "4513355" "5041396").PN.	USPAT	2002/07/14
				19:24
25	3	5943217.URPN.	USPAT	2002/07/14
				19:31
26	8	("4087906" "4435741" "4752027"	USPAT	2002/07/14
		"4893174" "4899207" "4982265"		19:31
		"5167361" "5425647").PN.	USPAT	2002/07/14
27	15	5789810.URPN.	USPAI	19:37
0.0	8	("3962899" "4113522" "4145903"	USPAT	2002/07/14
28	l °	"4177665" "5023398" "5233225"	0022	19:39
		"5397917" "5455457").PN.		
29	38	(257/697 438/612) and (pin with	USPAT;	2002/07/14
129	"	(attachment attaching attached) with pad)	US-PGPUB;	19:46
		(accusiness accusings)	EPO; JPO;	
			DERWENT	
30	11	(257/697 438/612) and (pin with	USPAT;	2002/07/14
	-	(attachment attaching attached) with pad	US-PGPUB;	19:55
		with solder)	EPO; JPO;	
			DERWENT	
31	1	6214642.URPN.	USPAT	2002/07/14
				19:52
32	9	("5436503" "5521435" "5598036"	USPAT	2002/07/14
		"5641996" "5666008" "5705858" "5708304" "5834848" "5912507").PN.		19.55
			USPAT;	2002/07/14
33	27	((257/697 4367612) and (pin with (attachment attaching attached) with	US-PGPUB;	19:55
		pad)) not ((257/697 438/612) and (pin	EPO; JPO;	
		with (attachment attaching attached) with	DERWENT	
		pad with solder))		
34	242	(solder adj (resist mask)) near3 (polymer	USPAT;	2002/07/14
"		polymeric plastic polyimide)	US-PGPUB;	20:33
			EPO; JPO;	
			DERWENT	2002/07/14
35	9	(257/697 438/612) and ((solder adj	USPAT; US-PGPUB;	19:59
		(resist mask)) near3 (polymer polymeric	EPO; JPO;	10.00
		plastic polyimide))	DERWENT	
10	429	flux near2 (polymer polymeric plastic	USPAT;	2002/07/14
42	429	polyimide)	US-PGPUB;	20:36
	1	Portrurae,	EPO; JPO;	
			DERWENT	
43	1	((solder adj (resist mask)) near3	USPAT;	2002/07/14
133	1	(polymer polymeric plastic polyimide))	US-PGPUB;	20:34
	1	with flux	EPO; JPO;	j
1			DERWENT	2002/07/14
44	3	(257/697 438/612) and (flux near2	USPAT;	2002/07/14
		(polymer polymeric plastic polyimide))	US-PGPUB; EPO; JPO;	20.33
	1		DERWENT	
1	_	(flux near2 (polymer polymeric plastic	USPAT;	2002/07/14
45	2	(flux near2 (polymer polymeric plastic polyimide) and (pin adj grid adj array)	US-PGPUB;	20:36
		polyimide) and (bin ad) dird ad) array)	EPO; JPO;	
		!	DERWENT	
46	771	flux near3 (polymer polymeric plastic	USPAT;	2002/07/14
30	''	polyimide)	US-PGPUB;	20:37
		F1	EPO; JPO;	
			DERWENT	

		(257/697 438/612) and (flux near3	USPAT;	2002/07/14
7	5	(257/69/ 438/612) and (flux neuro	US-PGPUB;	20:42
1		(polymer polymeric plastic polyimide))	EPO; JPO;	
į			DERWENT	
		0 / 1	USPAT;	2002/07/14
8	0	cyclohexyldiepoxide near3 (polymer		20:43
٥	1.	polymeric plastic polyimide)	US-PGPUB;	20.45
		porimora i	EPO; JPO;	
1	1		DERWENT	
1	_	1 hamildi enevi de	USPAT;	2002/07/14
9	6	cyclohexyldiepoxide	US-PGPUB;	20:43
			EPO; JPO;	
	i		DERWENT	
ļ			USPAT;	2002/07/12
į	52	(providing near3 substrate) and		16:18
j	-	(/	US-PGPUB;	10.10
Ì		(encapsulant encapsulating encapsulated	EPO; JPO;	
1		sealing)	DERWENT	(07 (10
1		("5249100" "6300678").PN.	USPAT	2002/07/12
	2	("5249100" 6300070 /:240		15:58
			USPAT	2002/07/12
	6	5249100.URPN.	"	15:59
			USPAT	2002/07/12
I	4	("3645785" "3855693" "4702941"	OSPAI	15:59
·	3	"4918811").PN.	1	
i	,	6300678.URPN.	USPAT	2002/07/12
-	1	0200010.0VEN.		16:00
		"" 1 " 1 " 1 " 1 " 1 " 1 " 1 " 1 " 1 "	USPAT	2002/07/12
- !	9	("4949455" "5041901" "5061552"		16:00
į	!	"5145104" "5334804" "5410807"		
		"5533665" "5642261" "5912510").PN.	USPAT	2002/07/12
	9	/!!4040455" "5041901" "5061552"	USPAI	16:02
-		HE1/1510/H H5334804" "541080/"		16:02
		"5533665" "5642261" "5912510").PN.		1 (0.7 (0.0)
	_	3333000 3342202 552210	USPAT	2002/07/12
-	0	6413849.URPN.		16:02
		1 10705701 1154422391	USPAT	2002/07/12
_	8	("4634041" "4970570" "5442239"		16:03
	1	"5448016" "5640052" "5718367"		
		"6054652" "6077725").PN.	11CD3/III	2002/07/12
	17		USPAT	16:04
-	1	30.000		=
		6054652.URPN.	USPAT	2002/07/12
-	2	6054652.0KIN.		16:08
		("4634041" "4970570" "5442239"	USPAT	2002/07/12
_	8	("4634041" "4970570 5412255		16:09
	}	"5448016" "5640052" "5718367"		1
	1	"6054652" "6077725").PN.	USPAT	2002/07/12
_	0		05171	16:09
_			TICD NO.	2002/07/12
	8	("4634041" "4970570" "5442239"	USPAT	l .
-	•	"5448016" "5640052" "5718367"	1	16:09
		"6054652" "6077725").PN.		10-110
		1	USPAT	2002/07/12
_	4	("5421083" "5432075 5545555		16:09
		"5834705").PN.	USPAT;	2002/07/12
_	5986	((pin adj grid adj array) pga) and	US-PGPUB;	
_		(method process)		
		1	EPO; JPO;	
			DERWENT	2002/07/12
		(((pin adj grid adj array) pga) and	USPAT;	1
_	170	(method process)) and jig	US-PGPUB;	
		(method process)) and Jry	EPO; JPO;	1
	1		DERWENT	!
		h	USPAT;	2002/07/12
	5.5	((((pin adj grid adj array) pga) and	US-PGPUB;	
-		(method process)) and jig) and polymer	EPO; JPO;	
1		/		1
i	1		DERWENT	2002/07/12
1		(((((pin adj grid adj array) pga) and	USPAT;	2002/07/12
-	50	(((((pin ad) grid ad) alidy) pad, (method process)) and jig) and polymer)	US-PGPUB;	16:15
1		(method process)) and jig/ and polymon)	EPO; JPO;	;
1	1	t //macriding near Substitute and	DERWENT	
		1 // / bing coldering nears pin/ and	I	
		(encapsulant encapsulating encapsulated		
1	i	sealing))	1	

-	12	((((((pin adj grid adj array) pga) and (method process)) and jig) and polymer) not ((providing near3 substrate) and ((attaching soldering) near3 pin) and (encapsulant encapsulating encapsulated sealing))) and substrate and solder and	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:16
-	107	pad (providing near3 substrate) and ((attaching soldering) near3 pin)	USPAT; US-PGPUB; EPO; JPO;	2002/07/12
_	2	(providing near3 substrate) and ((attaching soldering) near3 pin) and (applying near3 polymer)	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:31
_	18	((attaching soldering) near3 pin) and (applying near3 (polymer polymeric polyimide plastic))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/12 16:33

L	Hits	Search Text	DB	Time stamp
Number		257/607 420/612	USPAT;	2002/07/14
L	2998		US-PGPUB; EPO; JPO;	19:10
2	56	/257/697 438/612) and jig	DERWENT USPAT; US-PGPUB; EPO; JPO;	2002/07/14 18:48
3	12	("4021838" "4074342" "4338621" "4561006" "4823234" "4866841" "4893174" "4953060" "5006922"	DERWENT USPAT	2002/07/14 18:53
4	4	"5016087" "5025347" "5266912").PN. 5485039.URPN.	USPAT	2002/07/14
5	2	3654694.URPN.	USPAT	2002/07/14 18:56
6	7	6001724.URPN.	USPAT	2002/07/14
7	0	6165888.URPN.	USPAT	2002/07/14 18:59 2002/07/14
8	21	("4603802" "4661192" "4907734" "5014111" "5201454" "5249450" "5293073" "5302550" "5421503" "5550407" "5558270" "5633204" "5740956" "5871141" "5874780" "5884830" "5938105" "6001724" "6041995" "6080651" "6098868").PN.	USPAT	18:59
9	13	5874780.URPN.	USPAT	2002/07/14
10	1	6204089.URPN.	USPAT	2002/07/14 19:07 2002/07/14
11	9	("5376584" "5468655" "5478007" "5795818" "5854514" "5874780" "5894173" "5916407" "6005292").PN.	USPAT	19:07
12	1	"5874780".PN.	USPAT	19:08
13	7	("5037780" "5070604" "5348214" "5410807" "5478007" "5518964" "5615824").PN.	USPAI	19:09
14	1121		USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14
15	790	257/697 and (method process)	USPAT; US-PGPUB; EPO; JPO;	2002/07/14
16	422	(257/697 and (method process)) and solder and pad	DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 19:12
17	29	((257/697 and (method process)) and solder and pad) and pin	USPAT; US-PGPUB; EPO; JPO; DERWENT	
18	28	(((257/697 and (method process)) and solder and pad) and pin) not ((257/697 438/612) and jig)	USPAT; US-PGPUB; EPO; JPO; DERWENT	
19	1	"4498725" "4773873" "4950980" "5384692" "5637008" "5669774" "5691041" "5707247" "5714803" "5749999" "5766021" "5783461" "5805419" "5808474" "5812378"	USPAT	2002/07/14
20		"6069023").PN. 1 6229207.URPN.	USPAT	2002/07/14 19:21

21	1	6229207.URPN.	USPAT	2002/07/14 19:21
:-	_		***CD3M	2002/07/14
.2	20	("4170472" "4290079" "4824009"	USPAT	19:21
2		"5102829" "5237130" "5288944" \		19:21
ļ		"5303862" "5468995" "5541450"		
į		"E625166" "5625944" "5640047"		
ì		"E6/1990" "5831336" "5834839"		
1		"5847929" "5868304" "5907187"		
		"5938862" "5959348").PN.		
1			USPAT	2002/07/14
23	15	5288944.URPN.		19:23
Į.		("4338621" "4513355" "5041396").PN.	USPAT	2002/07/14
24	3	("4338621" "4513355 5041550 / 1211		19:24
			USPAT	2002/07/14
25	3	5943217.URPN.	•	19:31
			USPAT	2002/07/14
26	8	("4087906" "4435741" "4752027"	ODITAL	19:31
		"4893174" "4899207" "4982265"	1	
		"5167361" "5425647").PN.	TICDAT	2002/07/14
27	15	5789810.URPN.	USPAT	19:37
- 1			110020	2002/07/14
20	8	("3962899" "4113522" "4145903"	USPAT	
28	"	"4177665" "5023398" "5233225"		19:39
	Į į	"5397917" "5455457").PN.		2002/07/14
	38	/ Activities 439/612) and (pin With	USPAT;	2002/07/14
29	30	(attachment attaching attached) with pad)	US-PGPUB;	19:46
		(accacimiente accacimiente	EPO; JPO;	
			DERWENT	
		(257/697 438/612) and (pin with	USPAT;	2002/07/14
30	11	(257/69/ 438/612) and (pin with (attachment attaching attached) with pad	US-PGPUB;	19:55
		(attachment attaching attached, "151 pau	EPO; JPO;	
		with solder)	DERWENT	
			USPAT	2002/07/14
31	1	6214642.URPN.	1	19:52
		WEEDOOG CH	USPAT	2002/07/14
32	9	("5436503" "5521435" "5598036"	OSIAI	19:53
J.	1	1 115 (41006" "5666008" "5705858"		
		"5708304" "5834848" "59125U/")·PN·	USPAT;	2002/07/14
33	27	1,1257/607 438/612) and (pin With	US-PGPUB;	19:55
JJ	"	/ / chmont attaching attached) Willi		15.55
		1 11 11 and (PIII	EPO; JPO;	
	1	with (attachment attaching attached) with	DERWENT	
		l di+h golder))		2002/07/14
	242	(resist mask)) near3 (polymer	USPAT;	
34	242	polymeric plastic polyimide)	05 10111	19:59
		botametre brancio bariament	EPO; JPO;	
			DERWENT	1
		(257/697 438/612) and ((solder adj	USPAT;	2002/07/14
35	9	(25//69/ 438/012) and ((301der da)	US-PGPUB;	19:59
		(resist mask)) near3 (polymer polymeric	EPO; JPO;	
	Ì	plastic polyimide))	DERWENT	
		a limited and	USPAT;	2002/07/12
_	52	(providing near3 substrate) and	US-PGPUB;	1
1		//ching soldering) near3 pln/ and	EPO; JPO;	
		(encapsulant encapsulating encapsulated	DERWENT	
		acaling)	USPAT	2002/07/12
	2	1	USPAI	15:58
_	1	,	TICDAM.	2002/07/12
1		5 5249100.URPN.	USPAT	15:59
-	'			2002/07/12
		4 ("3645785" "3855693" "4702941"	USPAT	
-	1	4 ("3645785" "3655695" 4762914 "4918811").PN.		15:59
			USPAT	2002/07/12
-		1 6300678.URPN.		16:00
1		9 ("4949455" "5041901" "5061552"	USPAT	2002/07/12
1 -		9 ("4949455" "5041901" 5001332		16:00
		"5145104" "5334804" "5410807"		
		"5543665" "5642261" "5912510").PN.	USPAT	2002/07/12
1_		0 / 4040455		16:02
		"5533665" "5642261" "5912510 /.FM.	USPAT	2002/07/12
1	1	0 6413849.URPN.	OBEAL	16:02
1				

		1 "5442239"	USPAT	2002/07/12
_	8	("4634041" "4970570" "5442239"	0017.12	16:03
ı	i	"5448016" "5640052" "5718367"		
į		"6054652" "6077725").PN.		2002/07/12
1	17	5640052.URPN.	USPAT	
-	1/	3640032.0KtM.	Ţ	16:04
			USPAT	2002/07/12
_	2	6054652.URPN.		16:08
	ľ		USPAT	2002/07/12
	8	("4634041" "4970570" "5442239"	USPAI	16:09
_		"5448016" "5640052" "5718367"		10.09
		"6054652" "6077725").PN.		
	_	0034632 1 0077720 7 1201	USPAT	2002/07/12
_	0	6413849.URPN.		16:09
		U.S. 440020H	USPAT	2002/07/12
	8	("4634041" "4970570" "5442239"	USPAI	16:09
-	"	"5448016" "5640052" "5718367"		16:09
		"6054652" "6077725").PN.		
	. 1	("5421083" "5432675" "5543586"	USPAT	2002/07/12
-	4	("5421083" "5432673" 3343666"		16:09
		"5834705").PN.	USPAT;	2002/07/12
	5986	((pin adj grid adj array) pga) and		16:14
_		(method process)	US-PGPUB;	10.17
	1	(meerica process)	EPO; JPO;	
			DERWENT	
		and	USPAT;	2002/07/12
_	170	(((pin adj grid adj array) pga) and	US-PGPUB;	16:14
		(method process)) and jig		1 10.1.
			EPO; JPO;	
			DERWENT	
		us and and array) noal and	USPAT;	2002/07/12
_	55	((((pin adj grid adj array) pga) and	US-PGPUB;	16:14
		(method process)) and jig) and polymer	EPO; JPO;	
		,		
			DERWENT	0000 (07 (10
		(((((pin adj grid adj array) pga) and	USPAT;	2002/07/12
-	51	(method process)) and jig) and polymer)	US-PGPUB;	16:15
		(method process)) and jig/ and polyment	EPO; JPO;	Ì
		not ((providing near3 substrate) and	DERWENT	ļ
		(/-++-ching soldering) near3 pln) and	DEKMENT	
		(encapsulant encapsulating encapsulated		
		sealing))		1
		1 11	USPAT;	2002/07/12
-	12	(((((pin ad) gild ad) alld) pyd nolymer)	US-PGPUB;	16:16
		(method process)) and jig) and polymer)	EPO; JPO;	
		not //providing near3 substrate) and		
		1 //	DERWENT	
		/	1	ļ
		(encapsulant encapsulating on solder and		
1		sealing))) and substrate and solder and	1	
1		nad	USPAT;	2002/07/12
	107	(providing near3 substrate) and		16:18
i -	10,	((attaching soldering) near3 pin)	US-PGPUB;	16:10
		((accaching bords=119)	EPO; JPO;	1
1			DERWENT	
Į.	1		USPAT;	2002/07/12
1	1 2	(providing near3 substrate) and		16:31
-	1	(attaching soldering) nears pin) and	US-PGPUB;	10.51
1		(applying near3 polymer)	EPO; JPO;	
1		(abbiling means becames)	DERWENT	
		none man and	USPAT;	2002/07/12
_	18	((attaching soldering) near3 pin) and	US-PGPUB;	16:33
1		(applying near3 (polymer polymeric		1
		polyimide plastic))	EPO; JPO;	1
		POT 1 F =	DERWENT	i